



Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U5G9NJH6Q	EORM*476XXXZ	A	9991	2023-12-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	496.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	13x13	216	bulk solder	
Comment	Package : A0L2 TFBGA 13X13X1.2 216L P 0.8 MM 8373526			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EORM*476XXXZ				5999999.0	1000000.6				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	15.280	mg	supplier	die	Silicon (Si)	7440-21-3		14.162	mg	926832	28552				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.124	mg	8115	250				
				supplier	metallization	Copper (Cu)	7440-50-8		0.368	mg	24084	742				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.002	mg	131	4				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.063	mg	4123	127				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.016	mg	1047	32				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	131	4				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.088	mg	5759	177				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.455	mg	29777	917				
				Substrate (A313710)	Copper & its alloys	159.778	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Non-disclosure		9.587	mg	60000	19328
supplier	BT-substrate	Glass cloth	65997-17-3						59.278	mg	371000	119511				
supplier	BT-substrate	Copper foil	7440-50-8						73.019	mg	457000	147215				
supplier	Solder mask	Solvent naphtha (petroleum), heavy arom	64742-94-5						5.672	mg	35500	11436				
supplier	Solder mask	Propanol, 1(or 2)-(2-methoxymethylethoxy)-	34590-94-8						5.592	mg	35000	11275				
supplier	Solder mask	Aromatic carbonyl compounds	Trade secret						5.353	mg	33500	10791				
supplier	Solder mask	Copper,[29H,31H-phthalocyaninato(2-)-.kappa	147-14-8						1.039	mg	6500	2094				
supplier	Solder mask	Phenol, 2,6-bis(1,1-dimethylethyl)-4-methyl-	128-37-0						0.240	mg	1500	483				
DAF (2100AC)	M-011 Other inorganic materials	8.326	mg					supplier	film	Copper (Cu)	7440-50-8		6.893	mg	827850	13897
								supplier	film	Silver (Ag)	7440-22-4		0.640	mg	76850	1290
				supplier	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9		0.307	mg	36900	619				
				supplier	film	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)pe	Trade secret		0.224	mg	26900	452				
				supplier	film	2-[[[2,2-bis[[[(1-oxoallyl)oxy]methyl]butoxy]met	94108-97-1		0.216	mg	26000	436				
				supplier	film	tert-butyl peroxyneodecanoate	26748-41-4		0.042	mg	5000	84				
				supplier	film	Hydroquinone	123-31-9		0.004	mg	500	8				
Bonding wire (Au)	Precious metals	1.190	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		1.190	mg	1000000	2399				
Encapsulation (G1250AAS ULA)	M-011 Other inorganic materials	269.406	mg	supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-1,1'-biphenyl)-4,4'	85954-11-6		10.776	mg	40000	21726				
				supplier	Molding Compound	Epoxy resin	Trade secret		242.465	mg	900000	488842				
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		15.087	mg	56000	30417				
				supplier	Molding Compound	Phenol resin	Trade secret		1.078	mg	4000	2173				
Solder balls (SACN305)	Solder	42.021	mg	supplier	Solder	Tin (Sn)	7440-31-5		40.529	mg	964500	81712				
				supplier	Solder	Silver(Ag)	7440-22-4		1.261	mg	30000	2542				
				supplier	Solder	Copper (Cu)	7440-50-8		0.210	mg	5000	424				
				supplier	Solder	Nickel (Ni)	7440-02-2		0.021	mg	500	42				